## $>$ General Description

This PAN40SV52V N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology canprovide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.
$>$ Feature

- Super Low Gate Charge
-100\% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
-Advanced high cell density Trench technology


## DFN3X3A-EP1




## - Application

-DC/DC Primary Side Switch

- Industrial Synchronous
- Rectification Load Switch
-DC/DC Converters


## $>$ Absolute Maximum Ratings

| Parameter | Symbol | Rating | Units |
| :---: | :---: | :---: | :---: |
| Drain-Source Voltage | Vds | 40 | V |
| Gate-Source Voltage | VGS | $\pm 20$ | V |
| Continuous Drain Current ${ }_{1}$ | Io@Tc=25º | 43 | A |
| Continuous Drain Current1 | l @ $\mathrm{Tc}=100^{\circ} \mathrm{C}$ | 28 | A |
| Pulsed Drain Current2 | Idm | 60 | A |
| Single Pulse Avalanche Energy ${ }^{\text {a }}$ | EAS | 48 | mJ |
| Avalanche Current | las | 31 | A |
| Total Power Dissipation4 | Po@Tc=25 ${ }^{\circ} \mathrm{C}$ | 27.8 | W |
| Storage Temperature Range | Tsta | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |
| Operating Junction Temperature Range | TJ | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |
| Thermal Resistance Junction-ambient (Steady State) ${ }^{\text {1 }}$ | RөjA | 60 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Thermal Resistance Junction-Case ${ }_{1}$ | Rөлс | 4.5 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

## Electrical Characteristics ( $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ Unless otherwise noted)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Drain-Source Breakdown Voltage | BVoss | VGs=0V , Id=250uA | 40 | --- | --- | V |
| Static Drain-Source On-Resistance2 | Rds(On) | VGS $=10 \mathrm{~V}$, ID=12A | --- | 6.9 | 8.5 | $\mathrm{m} \Omega$ |
|  |  | VGs=4.5V , Id=10A | --- | 10.5 | 15 |  |
| Gate Threshold Voltage | VGS(th) | VGs=Vds, Id =250uA | 1.0 | 1.5 | 2.5 | V |
| Drain-Source Leakage Current | ldss | Vos $=32 \mathrm{~V}$, VGs $=0 \mathrm{~V}$, $\mathrm{TJ}=25^{\circ} \mathrm{C}$ | --- | --- | 1 | uA |
|  |  | Vds $=32 \mathrm{~V}$, $\mathrm{VGs}=0 \mathrm{~V}, \mathrm{TJ}=55^{\circ} \mathrm{C}$ | --- | --- | 5 |  |
| Gate-Source Leakage Current | Igss | $\mathrm{V}_{\mathrm{GS}}= \pm 20 \mathrm{~V}$, $\mathrm{V}_{\mathrm{DS}}=0 \mathrm{~V}$ | --- | --- | $\pm 100$ | nA |
| Gate Resistance | Rg | V dS $=0 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | --- | 1.7 | --- | $\Omega$ |
| Total Gate Charge (4.5V) | $\mathrm{Q}_{\mathrm{g}}$ | Vds=20V , VGs=4.5V , ld=12A | --- | 5.8 | --- | nC |
| Gate-Source Charge | Qgs |  | --- | 3 | --- |  |
| Gate-Drain Charge | Qgd |  | --- | 1.2 | --- |  |
| Turn-On Delay Time | Td(on) | $\begin{aligned} & V_{D D}=15 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}, \\ & \mathrm{R}_{\mathrm{G}}=3.3 \Omega \mathrm{ID}=1 \mathrm{~A} \end{aligned}$ | --- | 14.3 | --- | ns |
| Rise Time | Tr |  | --- | 5.6 | --- |  |
| Turn-Off Delay Time | $\mathrm{Td}_{\text {doff) }}$ |  | --- | 20 | --- |  |
| Fall Time | $\mathrm{T}_{\mathrm{f}}$ |  | --- | 11 | --- |  |
| Input Capacitance | Ciss | $\mathrm{V} \mathrm{DS}=15 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | --- | 690 | --- | pF |
| Output Capacitance | Coss |  | --- | 193 | --- |  |
| Reverse Transfer Capacitance | Crss |  | --- | 38 | --- |  |

## Diode Characteristics

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
| :--- | :---: | :--- | :---: | :---: | :---: | :---: |
| Continuous Source Current 1,5 | Is | $\mathrm{V}_{\mathrm{G}}=\mathrm{V}=0 \mathrm{~V}$, Force Current | --- | --- | 20 | A |
| Diode Forward Voltage 2 | VSD | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{IS}=1 \mathrm{~A}, \mathrm{~T}=25^{\circ} \mathrm{C}$ | --- | --- | 1 | V |

Note:
1.Pulse width limited by maximum junction temperature.
2.The data tested by pulsed, pulse width $\leqq 300$ us, duty cycle $\leqq 2 \%$
3.The EAS data shows Max. rating . The test condition is $\mathrm{V}_{\mathrm{DD}}=25 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{~L}=0.1 \mathrm{mH}, \mathrm{I}_{\mathrm{AS}}=31 \mathrm{~A}$
4.Ensure that the channel temperature does not exceed $150^{\circ} \mathrm{C}$.
5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

PAN40SV52V

Typical Characteristics


Fig. 1 Typical Output Characteristics


Fig. 3 Source Drain Forward Characteristics


Fig. 5 Normalized $V_{G S(t h)}$ vs. $T_{J}$


Fig. 2 On-Resistance vs. G-S Voltage


Fig. 4 Gate-Charge Characteristics


Fig. 6 Normalized RDSon vs. $T_{J}$

PAN40SV52V
N-Ch 40V Fast Switching MOSFET
Vos $=40 \mathrm{~V}$, $\mathrm{Id}=43 \mathrm{~A}$, RDS $(0 \mathrm{~N})=8.5 \mathrm{~m} \Omega$


Fig. 7 Capacitance


Fig. 8 Safe Operating Area


Fig. 9 Normalized Maximum Transient Thermal Impedance


Fig. 10 Switching Time Waveform


Fig. 11 Unclamped Inductive Waveform

## $>$ Recommand IR Reflow Soldering Thermal Profile



| Profile Feature | Pb-Free Assembly Profile |
| :--- | :---: |
| Temperature Min. (Tsmin) | $150^{\circ} \mathrm{C}$ |
| Temperature Max. (Tsmax) | $200^{\circ} \mathrm{C}$ |
| Time (ts) from (Tsmin to Tsmax) | $60-120$ seconds |
| Average Ramp-up Rate (tLto tP) | $3^{\circ} \mathrm{C} /$ second max. |
| Liquidous Temperature (TL) | $217^{\circ} \mathrm{C}$ |
| Time (tL) Maintained Above (TL) | $60-150$ seconds |
| Peak Temperature | $260^{\circ} \mathrm{C}+0^{\circ} \mathrm{C} /-5^{\circ} \mathrm{C}$ |
| Time (tP) within $5^{\circ} \mathrm{C}$ of actual Peak Temperature | 30 seconds |
| Ramp-down Rate (TP to TL) | $6^{\circ} \mathrm{C} /$ second max |
| Time $25^{\circ} \mathrm{C}$ to Peak Temperature | 8 minutes max. |

## Ordering Information

| Part Number | Description | Quantity |
| :---: | :---: | :---: |
| PAN40SV52V | DFN3X3A-EP1 Reel | 3000 pcs |

PAN40SV52V

## N-Ch 40V Fast Switching MOSFET <br> $V_{D s}=40 \mathrm{~V}, \mathrm{Id}=43 \mathrm{~A}, \mathrm{RDS}(0 \mathrm{~N})=8.5 \mathrm{~m} \Omega$

## $>$ Package Information (DFN3X3A-EP1)



| SYMBOLS | MILLIMETERS |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |
| A | 0.70 | 0.85 | 0.027 | 0.034 |
| b | 0.20 | 0.40 | 0.007 | 0.016 |
| C | 0.10 | 0.25 | 0.004 | 0.010 |
| D | 3.15 | 3.45 | 0.124 | 0.136 |
| D1 | 2.90 | 3.20 | 0.114 | 0.126 |
| D2 | 1.54 | 1.98 | 0.060 | 0.080 |
| D3 | 0.10 | 0.30 | 0.004 | 0.012 |
| E | 3.15 | 3.45 | 0.124 | 0.136 |
| E1 | 3.00 | 3.25 | 0.118 | 0.128 |
| E2 | 2.29 | 2.65 | 0.090 | 0.104 |
| e | 0.65 BSC |  | 0.025 BSC |  |
| H | 0.28 | 0.65 | 0.011 | 0.026 |
| $\Theta$ | $0^{\circ}$ | $14^{\circ}$ | $0^{\circ}$ | $14^{\circ}$ |
| L | 0.30 | 0.50 | 0.012 | 0.020 |
| L1 | 0.13 |  | 0.005 |  |
| M | --- | 0.15 | --- | 0.006 |

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